



Product Change Notification

Change Notification #: 116875 - 00
Change Title: Intel® RAID Adapter RSP3TD160F,
 Intel® RAID Adapter RSP3MD088F,
 PCN 116875-00, Product Design,
 Resistor change and firmware update
Date of Publication: April 03, 2019

Key Characteristics of the Change:

Product Design

Forecasted Key Milestones:

Date Customer Must be Ready to Receive Post-Conversion Material: *	April 18, 2019
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*Intel appreciates the customer's desire to receive the latest revision of products. However, Intel manages inventory on a first in first out (FIFO) basis at the MM# level. Subsequently, customer requests for a specific revision of material (below the MM#) will not be supported by Intel.

Description of Change to the Customer:

Intel is implementing the following changes on the Intel® RAID Adapters RSP3TD160F and RSP3MD088F:

1. Change in resistor placement in the memory voltage regulator circuit order to allow 1.8V NOR flash memory. This is to allow a second source memory vendor.
2. Depopulate pull-up resistor in the Supercap charge circuit to increase charge circuit margin.
3. Update the firmware to version 5.050.00-1367 (MR 7.5p2 on firmware package 50.5.2-1326).

Customer Impact of Change and Recommended Action:

Intel does not expect any impact to customers from this change. Customers may need to validate the function and feature change once the post-change system is available.

Please contact your local Intel Field Sales Rep if you have any further questions about these changes.

Products Affected / Intel Ordering Codes:

Product Code	MM#	Pre Change TA	Pre Change PBA	Post Change TA	Post Change PBA
RSP3TD160F	954493	J40741-003	J40742-202	J40741-004	J40742-203
RSP3MD088F	954551	J40747-003	J40748-202	J40747-004	J40748-203

PCN Revision History:

Date of Revision: April 3, 2019	Revision Number: 00	Reason: Originally Published PCN
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116875 - 00

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Should you have any issues with the timeline or content of this change, please contact the Intel Representative(s) for your geographic location listed below. No response from customers will be deemed as acceptance of the change and the change will be implemented pursuant to the key milestones set forth in this attached PCN.

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